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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Date : 12/15/2004  
IN RE APPLICATION OF: TAN, CHONG AIK et al.  
APPLN. NO. : 09/736462  
FILED : 12/15/2000  
FOR : BUMP CHIP LEAD FRAME AND PACKAGE  
EXAMINER : Hung V. Ngo  
Phone : (703) 308-7614  
Group : 2831

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STATUS INQUIRY

Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

S I R :

Applicant(s) respectfully inquire as to the status of the  
above-identified patent application. The last communication was:

Issue Fee Paid on June 11, 2004 in response to Notice of Allowance  
dated April 22, 2004; Applicants also filed a 312 Amendment and new  
Formal Drawings on June 2, 2004.

Please advise us of the current status of this application.

Respectfully submitted,

TAN, CHONG AIK et al.



ON Semiconductor  
Intellectual Property Dept.  
5005 E. McDowell Road-A700  
Phoenix, AZ 85008

Kevin B. Jackson, #38,502  
Phone: 480-244-4885  
Fax: 480-244-3169

FAY 12/15/04

